

### **In the Specification**

At page 4, lines 1 – 4, please replace the paragraph as follows (underlined denotes replacements additions and strikethrough notes deletions):

For failure analysis, thinning a flip-chip bonded die to such degrees is time consuming, burdensome, overly complex, and can damage the underlying circuitry that is to be analyzed for potential defects. ~~This~~These issues can be better appreciated through a discussion of the following common approach for such thinning.

At page 10, lines 12 – 23 and page 11, lines 1 – 3 , please replace the paragraph as follows (underlined denotes replacements additions and strikethrough notes deletions):

The system of FIG. 2 is used first to generate a reference profile for a designated surface in a nondefective die, referred to respectively as the “reference die” and the “reference surface.” Accordingly, the first beam splitter 220 is positioned between the reference die and the laser 210. The laser 210 is used to direct light of a known wavelength through the first beam splitter 220, with the first beam splitter 220 adapted redirect the light that is reflected by the surface 231 under evaluation within the die 202. The redirected light that is reflected by the surface 231 is received and split into two corresponding beams of light for detection by the detectors 228 and 230. The nIR analyzer 226 receives the two corresponding beams of light reflected from the reference die, via the detector 228, and generates a profile for the reference surface, for example, by determining the time-arrival differential and/or the intensity difference for the two beams. For further information discussing the characterization and analysis of these profiles, reference may be made to a text entitled, *Confocal Scanning Optical Microscopy and Related Imaging Systems*, by T.R. Corle and G.S. Kino.